

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	3963	((("light emitting device" "light emitting diode") near3 (chip die))	US-PGPUB; USPAT; JPO; DERWENT	2006/08/28 10:27
2	BRS	L10	474	L8 and (bond bonding) near3 layers	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
3	BRS	L11	247	10 and solder	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
4	BRS	L12	83	11 and barrier	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
5	BRS	L13	35	12 and (mirror reflector reflective reflection reflect)	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
6	BRS	L14	23	13 and (coupling protective)	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
7	BRS	L15	14	14 and @ad<"20030226"	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
8	BRS	L2	1348	L1 and bonding	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:39
9	BRS	L3	506	2 and solder	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
10	BRS	L4	141	3 and barrier	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
11	BRS	L5	111	4 and (mirror reflector reflective reflection reflect)	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
12	BRS	L6	70	5 and (coupling protective)	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40
13	BRS	L7	41	6 and @ad<"20030226"	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:40

	Type	L #	Hits	Search Text	DBs	Time Stamp
14	IS&R	L8	11353	(257/81,98,99,734,736,758,763,779,780,782).CCLS.	US-PGPUB; USPAT; EPO; DERWENT	2006/08/28 10:39